

7.0V to 9.5V

15mA(Typ)

0.005%(Typ)

2.3Vrms(Typ)

-100dB(Typ)

6µVrms(Typ)

2µVrms(Typ)

-40°C to +85°C

+0dB to -40dB

Sound Processor with Built-in 2-band Equalizer BD37512FS

General Description

BD37512FS is a sound processor with built-in 2-band equalizer for car audio. The functions are 4ch stereo input selector, input-gain control, main volume and 4ch fader volume. Moreover, its "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). "Advanced switch" makes control of microcomputer easier, supporting the construction of a high quality car audio system.

Features

- Reduce switching noise of mute, main volume, fader volume, bass, trebles by using advanced switch circuit
- Built-in 1 differential input selector and 3 single-ended input selectors.
- Built-in ground isolation amplifier inputs, ideal for external stereo input.
- Decrease the number of external components due to built-in 2-band equalizer filter.
- It is possible to adjust the gain of the bass and treble up to ±20dB with 1 dB step gain adjustment.
- Energy-saving design resulting in low current consumption, by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB layout.
- It is possible to control the I²C BUS by 3.3V / 5V.

Applications

It is optimal for use in car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

Key Specifications

- Power Supply Voltage Range:
- Circuit Current (No Signal):
- Total Harmonic Distortion:
- Maximum Input Voltage:
- Cross-talk Between Selectors:
- Volume Control Range:
- Output Noise Voltage:
- Residual Output Noise Voltage:
- Operating Temperature Range:

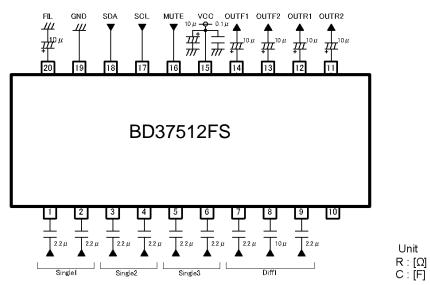
Package

W(Typ) x D(Typ) x H(Max)

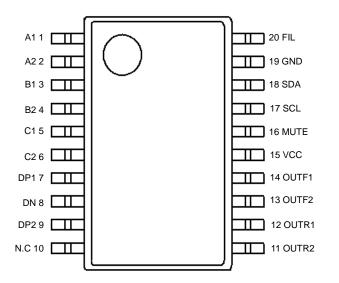


OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

Typical Application Circuit

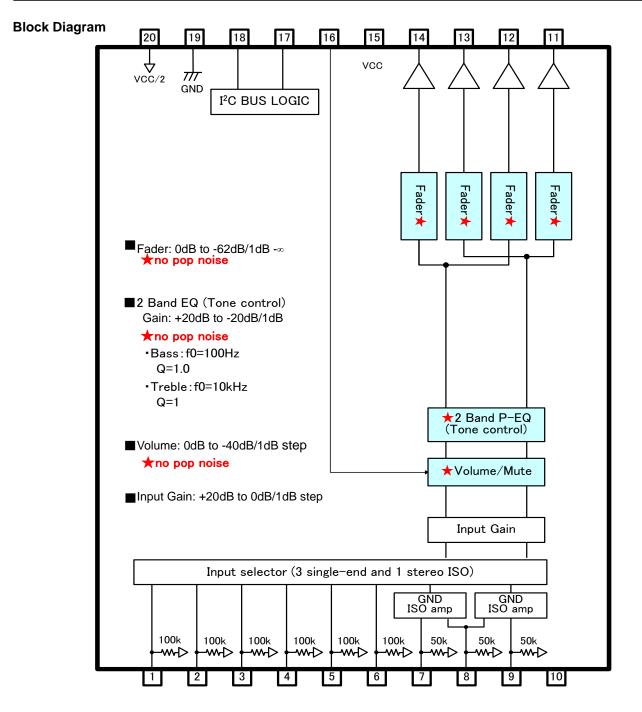


Pin Configuration



Pin Descriptions

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	11	OUTR2	Rear output terminal of 2ch
2	A2	A input terminal of 2ch	12	OUTR1	Rear output terminal of 1ch
3	B1	B input terminal of 1ch	13	OUTF2	Front output terminal of 2ch
4	B2	B input terminal of 2ch	14	OUTF1	Front output terminal of 1ch
5	C1	C input terminal of 1ch	15	VCC	Power supply terminal
6	C2	C input terminal of 2ch	16	MUTE	External compulsory mute terminal
7	DP1	D positive input terminal of 1ch	17	SCL	I ² C Communication clock terminal
8	DN	D negative input terminal	18	SDA	I ² C Communication data terminal
9	DP2	D positive input terminal of 2ch	19	GND	GND terminal
10	N.C.	No Connection	20	FIL	VCC/2 terminal



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	Vcc	10.0	V
Input Voltage	VIN	Vcc+0.3 to GND-0.3	V
Power Dissipation	Pd	0.94 ^(Note)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note) This value derates by 7.5mW/°C for Ta=25°C or more when ROHM standard board is used.

Thermal resistance θja = 133.3(°C/W) ROHM Standard board Size : 70 x 70 x 1.6(mm³)

Material : A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	V _{CC}	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

Electrical Characteristics

(Unless specified otherwise, Ta=25°C, V_{CC}=8.5V, f=1kHz, V_{IN} =1Vrms, Rg=600Ω, R_L=10kΩ, A input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, Fader 0dB)

			Limit				
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current	lq	-	15	30	mA	No signal
	Voltage Gain	Gv	-1.5	0	1.5	dB	Gv=20log(Vout/Vin)
	Channel Balance	СВ	-1.5	0	1.5	dB	$CB = G_{V1}-G_{V2}$
	Total Harmonic Distortion	THD+N1	-	0.005	0.05	%	V _{OUT} =1VRMS BW=400Hz-30KHz
RAL	Output Noise Voltage *	V _{NO1}	-	6	25	μVrms	Rg = 0Ω BW = IHF-A
GENERAL	Residual Output Noise Voltage *	VNOR	-	2	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Cross-talk Between Channels *	СТС	-	-100	-90	dB	$\label{eq:generalized_relation} \begin{split} &Rg = 0\Omega \\ &CTC {=} 20 log(V_{OUT} {/} V_{IN}) \\ &BW = IHF{-} A \end{split}$
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V _{RR} =100mVrms RR=20log(V _{CC} IN/V _{OUT})
	Input Impedance(A, B, C)	RIN_S	70	100	130	kΩ	
	Input Impedance (D)	R _{IN_D}	35	50	65	kΩ	
SELECTOR	Maximum Input Voltage	Vim	2.1	2.3	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
IT SELE	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	$\begin{array}{l} Rg = 0\Omega \\ CTS = 20 log(V_{OUT}/V_{IN}) \\ BW = IHF-A \end{array}$
INPUT	Common Mode Rejection Ratio *	CMRR	50	65	-	dB	DP1 and DN input DP2 and DN input CMRR=20log(VIN/VOUT) BW = IHF-A
GAIN	Minimum Input Gain	Gin_min	-2	0	+2	dB	Input gain 0dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
INPUT G	Maximum Input Gain	Gin_max	18	20	22	dB	Input gain 20dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
	Gain Set Error	G _{IN_ERR}	-2	0	+2	dB	GAIN=+1dB to +20dB

Electrical Characteristics - continued

X				Limit			
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
MUTE	Mute Attenuation *	G _{MUTE}	-	-105	-85	dB	Mute ON G _{MUTE} =20log(V _{OUT} /V _{IN}) BW = IHF-A
VOLUME	Maximum Attenuation	Gv_min	-43	-40	-37	dB	Volume = -40 dB Gv=20log(V _{OUT} /V _{IN})
OLU	Attenuation Set Error 1	G _{V_ERR1}	-2	0	+2	dB	GAIN & ATT=0dB to -15dB
×	Attenuation Set Error 2	G_{V_ERR2}	-3	0	+3	dB	ATT=-16dB to -40dB
(0)	Maximum Boost Gain	GB_BST	18	20	22	dB	Gain=+20dB f=100Hz V _{IN} =100mVrms G _B =20log (V _{OUT} /V _{IN})
BASS	Maximum Cut Gain	G _{B_CUT}	-22	-20	-18	dB	Gain=-20dB f=100Hz V _{IN} =2Vrms G _B =20log (V _{OUT} /V _{IN})
	Gain Set Error	Gb_err	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz
щ	Maximum Boost Gain	Gt_bst	18	20	22	dB	Gain=+20dB f=10kHz V _{IN} =100mVrms G _T =20log (V _{OUT} /V _{IN})
TREBLE	Maximum Cut Gain	G _{T_CUT}	-22	-20	-18	dB	Gain=-20dB f=10kHz V _{IN} =2Vrms Gτ=20log (V _{OUT} /V _{IN})
	Gain Set Error	Gt_err	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz
	Maximum Attenuation *	GF_MIN	-	-100	-90	dB	Fader = -∞dB G _F =20log(V _{OUT} /V _{IN}) BW = IHF-A
	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=0dB to -15dB
FADER	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB
FAL	Attenuation Set Error 3	GF_ERR3	-4	0	+4	dB	ATT=-48dB to -62dB
	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVms
	Maximum Output Voltage	Vом	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

Typical Performance Curves

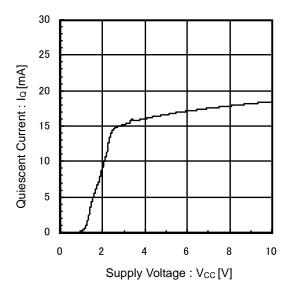
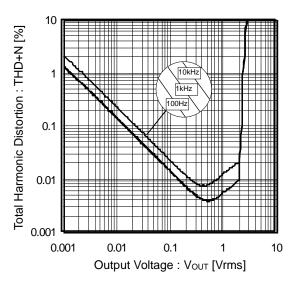


Figure 1. Quiescent Current vs Supply Voltage





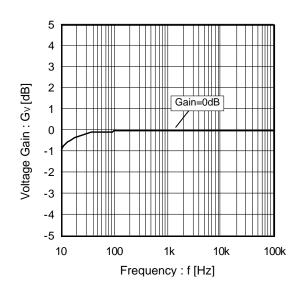


Figure 3. Voltage Gain vs Frequency

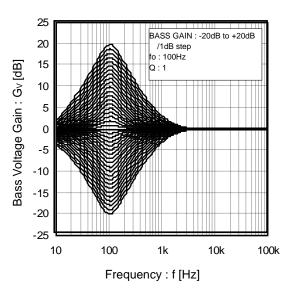


Figure 4. Bass Voltage Gain vs Frequency

Typical Performance Curves - continued

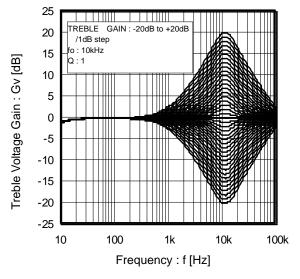


Figure 5. Treble Voltage Gain vs Frequency

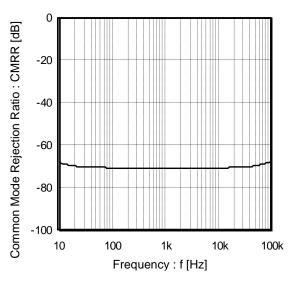


Figure 6. Common Mode Rejection Ratio vs Frequency

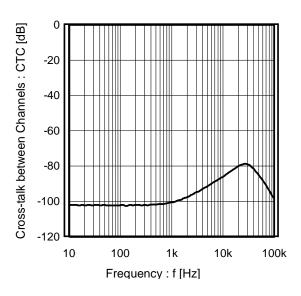


Figure 7. Cross-Talk between Channels vs Frequency

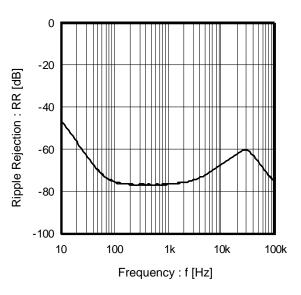


Figure 8. Ripple Rejection Ratio vs Frequency

Typical Performance Curves - continued

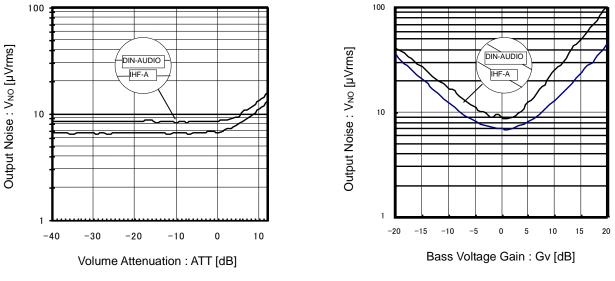
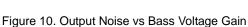


Figure 9. Output Noise vs Volume Attenuation



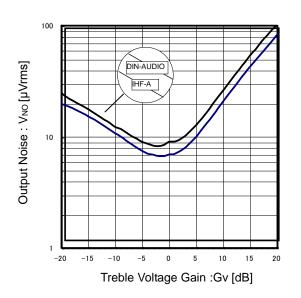


Figure 11. Output Noise vs Treble Voltage Gain

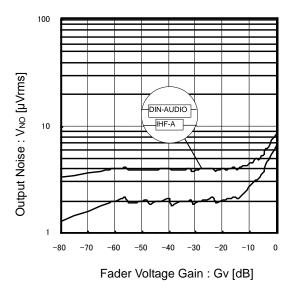


Figure 12. Output Noise vs Fader Voltage Gain

Typical Performance Curves - continued

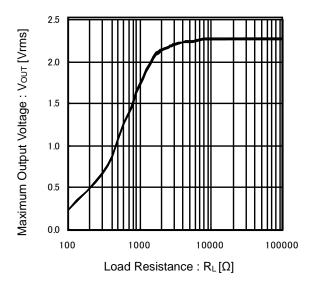


Figure 13. Maximum Output Voltage vs Load Resistance

	H2=2V AC 10:1			-	500us/div
HC IU.I	HC 10.1				NORM:2MS/s
OUTF1		NÅÅÅAA	MÅM	MANAN	WWW.MWW
ιŗ			MM		
			tttttt-	+	
4T 1.00ms 1/4T 1.00D00kl	Iz				
[™] OUTF2		A Å Å Å Å Å Å	MÅM	A Á Á A A A A	A A A A À A A A A A A A A A A A A A A A
st.	~~~~		halanan.		
	.,	ИŴМ	MAAN	(WWW)	ANAAAAAAAA
		1			

Figure 14. Advanced Switch 1

CH1=2V CH2=2V AC 10:1 AC 10:1	500us/div NORM:2MS/s
	OUTF1
ат 1.00ms 1/ат 1.00ms	
	OUTF2

Figure 15. Advanced Switch 2

Timing Chart

Control Signal Specification

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

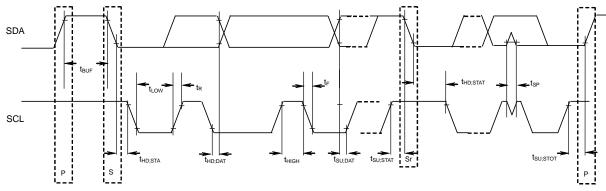


Figure 16. I²C-bus Signal Timing Diagram

Table 1 Characteristics of the SDA and SCL bus lines for I²C-bus devices

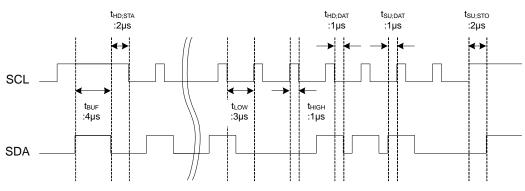
	Parameter	Symbol	Fast-mod	le l²C-bus	Unit	
	Faldineter	Symbol	Min	Max	Unit	
1	SCL clock frequency	f scL	0	400	kHz	
2	Bus free time between a STOP and START condition	t BUF	1.3	-	μS	
3	Hold time (repeated) START condition. After this period, the first clock	tur anu	0.6		μS	
3	pulse is generated	t _{hd;sta}	0.0	-	μο	
4	LOW period of the SCL clock	t∟ow	1.3	-	μS	
5	HIGH period of the SCL clock	tнigн	0.6	-	μS	
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS	
7	Data hold time:	t _{HD;DAT}	0.7 (Note)	-	μS	
8	Data set-up time	tsu;dat	700	-	ns	
9	Set-up time for STOP condition	tsu;sto	0.6	-	μS	

All values referred to VIH Min and VIL Max Levels (see Table 2).

(Note) To avoid sending right after the fall-edge of SCL (VIHmin of the SCL signal), the transmitting device should set a hold time of 300ns or more for the SDA signal. For 7(t_{HD;DAT}), 8(t_{SU;DAT}), make the setup in which the margin is fully in.

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Parameter	Sumbol	Fast-mode	Unit	
	Parameter	Symbol	Min	Max	Unit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	Vih	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	t _{SP}	0	50	ns
13	LOW level output voltage: at 3mA sink current	Vol1	0	0.4	V
14	Input current of each I/O pin with an input voltage between 0.4V and 4.5V.	h	-10	+10	μA



SCL clock frequency : 250 kHz

Figure 17. I²C Data Transmission Command Timing Diagram

(2) <u>I²C BUS FORMAT</u>

	MSB LSB	MS	SB L	SB	MSB	LSB			
S	Slave Address	А	Select Address	А		Data	A P		
 1bit	8bit	1bit	8bit	1bit		8bit	1bit 1bit		
	S = Start condition (Recognition of start bit)								
	Slave Address	= Recog	gnition of slave a	ddress. 7	The first 7	bits correspond	to the slave address	s.	
		The le	ast significant bit	is "L" w	hich corre	sponds to write	mode.		
	А	= ACKN	IOWLĚDGE bit (I	Recognit	ion of ack	nowledgement)			
	Select Address	= Select address corresponding to volume, bass or treble.							
	Data	= Data on every volume and tone.							
	Р	= Stop o	condition (Recogi	nition of a	stop bit)				

(3) <u>I²C BUS Interface Protocol</u>

<u>\</u> ~/ -											
S	Slave Addre	SS	А	Select Add	lress	Α	Data		Α	Р	
	MSB	LSB		MSB	LSB	Ν	1SB	LS	В		

(b)	Automatic Increment	(Se	elect Address increas	ses (+1)) accordin	g to	the number	of da	ata.)

	S	Sla	ve Address	А	Select A	Address	А	D	ata1	А	Data2	А		Dat	aN	А	Ρ	
	ſ	ИSВ	LSE	3	MSB	LSE	3 M	SB	LSB	MS	SB LS	В	Μ	SB	LS	В		
((Exan	nple)	1 Data1 sha	all be	e set as da	ata of add	ress	spec	ified by	Sele	ect Address.							
			2 Data2 sh	all b	e set as da	ata of add	ress	spec	ified by	Sele	ect Address ·	+1.						
			③ DataN sh	all b	e set as d	ata of add	ress	spec	cified by	Sele	ect Address	+N-1	Ι.					

		۲	Data				444	.000 op c	00		5100071					
(c) Co	onfigurati	on Un	avai	lable for -	Fransmissic	on (l	In this ca	ise, (only Se	elect Ad	dress1	is s	et.)		
3	5 5	lave Add	lress	Α	Select	Address1	А	Data	Α	Sele	ect Add	ress 2	Α	Data	Α	Ρ
	M	SB	LSE	3	MSB	LSB	N	ISB LS	B	MSB	LSB	MSB	LS	B		
		(Note)	If any	data	a is transr	mitted as Se	elec	t Addres	s 2	next to	data, i	t is reco	ogniz	zed		
			as	data	, not as S	Select Addre	ess	2.					-			

(4) Slave Address

ľ	MSB							LSB	
	A6	A5	A4	A3	A2	A1	A0	R/W	
	1	0	0	0	0	0	0	0	80H

(5) <u>Select Address & Data</u>

	Select	MSB			Da	ata			LSB		
Items	Address (hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advance d switch ON/OFF	0	Advance time Volume/To		0	0	Advance time o			
Input Selector	04	0	0								
Input gain	06	Mute ON/OFF	0	0			Input Gair	n			
Volume gain	20	1	0			Volume A	ttenuation				
Fader 1ch Front	28	1	0			Fader At	tenuation				
Fader 2ch Front	29	1	0			Fader At	tenuation				
Fader 1ch Rear	2A	1	0			Fader At	tenuation				
Fader 2ch Rear	2B	1	0			Fader At	tenuation				
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gai	n			
Treble gain	57	Treble Boost/ Cut	0	0			Treble Gai	in			
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. When changing a tone into the cut from the boost, or the cut and the boost, always go via the condition of the tone 0dB.
- 3. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

$$\longrightarrow 01 \rightarrow 04 \rightarrow 06 \rightarrow 20 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 51 \rightarrow 57$$

- 4. For the function of Input Selector etc, Advanced Switch is not used. Therefore, please apply mute on the set side when changing these settings.
- 5. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF while waiting for advanced-mute time.

Select address 01 (hex)

Mode	MSB		Adv	vanced swit	ch time of N	lute		LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	Advonced						0	0
1.2msec	Advanced Switch	0	Advanced	switch time	0	0	D1 0 0 1 1	1
2.4msec	ON/OFF		of Volume/	Tone/Fader	0	0	1	0
4.8msec							1	1

Mode	MSB				witch time c one/Fader	of		LSB
	D7	D6	D5	D4	D3	D2	D1	D0
4.6 msec	Advisional		0	0				
9.3 msec	Advanced Switch	0	0	1		0	Advance	ed switch
18.6 msec	ON/OFF	0	1	0	0	0	Time of Mute	
37.2 msec			1	1				

Mode	MSB		ļ	Advanced sv	vitch ON/OF	F		LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	Advanced	switch time	0	0	Advance	ed switch
ON	1	0	of Volume/	Tone/Fader	0	0	Time o	of Mute

Select address 04(hex)

Mode	MSB			Input Se	lector			LSB
wode	D7	D6	D5	D4	D3	D2	D1	D0
A						0	0	0
В						0	0	1
С		0				0	1	0
D	0		0	0	0	1	0	0
SHORT						1	0	1
INPUT MUTE						1	1	0
						1	1	1

: Initial condition

 $\begin{array}{l} \text{SHORT}: \text{The input impedance of each input terminal is lowered from 100k} \Omega(\text{TYP}) \text{ to 6 k} \Omega(\text{TYP}). \\ \text{(For quick charge of coupling capacitor)} \end{array}$

INPUT MUTE : Mute is done at the input signal part of Input Selector.

Select address 06 (hex)

Coin	MSB			Inpu	t Gain			LSB								
Gain	D7	D6	D5	D4	D3	D2	D1	D0								
0dB				0	0	0	0	0								
1dB				0	0	0	0	1								
2dB				0	0	0	1	0								
3dB				0	0	0	1	1								
4dB				0	0	1	0	0								
5dB				0	0	1	0	1								
6dB				0	0	1	1	0								
7dB				0	0	1	1	1								
8dB				0	1	0	0	0								
9dB				0	1	0	0	1								
10dB				0	1	0	1	0								
11dB	Mute			0	1	0	1	1								
12dB	ON/OFF	0	0	0	1	1	0	0								
13dB				0	1	1	0	1								
14dB				0	1	1	1	0								
15dB						0	1	1	1	1						
16dB						-	-	-			1	0	0	0	0	
17dB												1	0	0	0	1
18dB												1	0	0	1	0
19dB					1	0	0	1	1							
20dB				1	0	1	0	0								
				1	1	0	1	1								
Prohibition				:	:	:	:	:								
(Note) in case conding pro				1	1	1	1	1								

(Note) In case sending prohibited data, 0dB is set.

Mada	MSB			Mute	ON/OFF			LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	0			Innut Coin		
ON	1	0	0			Input Gain		

:Initial condition

Γ

Select address 20 (hex)

Gain & ATT	MSB			Vol Atte	enuation			LSB								
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0								
0dB			0	0	0	0	0	0								
-1dB			0	0	0	0	0	1								
-2dB			0	0	0	0	1	0								
•			•	•	•	•	•	•								
•			•	•	•	•	•	•								
•			•	•	•	•	•	•								
-38dB	1	0	1	0	0	1	1	0								
-39dB		Ű	1	0	0	1	1	1								
-40dB			1	0	1	0	0	0								
				. [Ę	F					1	0	1	0	0	1
Prohibition			:	:	:	:	:	:								
			1	1	1	1	1	0								
			1	1	1	1	1	1								

(Note) In case sending prohibited data, -40dB is set.

Select address 28, 29, 2A, 2B (hex)

Gain & ATT	MSB			Fader At	tenuation			LSB
Gairi & ATT	D7	D6	D5	D4	D3	D2	D1	D0
0dB			0	0	0	0	0	0
-1dB			0	0	0	0	0	1
-2dB			0	0	0	0	1	0
•			•	•	•	•	•	•
•	1	0	•	•	•	•	•	•
•			•	•	•	•	•	•
-61dB			1	1	1	1	0	1
-62dB			1	1	1	1	1	0
-∞dB			1	1	1	1	1	1

: Initial condition

Select address 51, 57 (hex)

Gain	MSB			Bass/Tre	eble Gain			LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Bass/			0	1	0	1	1
12dB	Treble	0	0	0	1	1	0	0
13dB	Boost	Ū.	°,	0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
]			1	0	1	0	1
Prohibition				:	:	:	:	:
i fornordori				1	1	1	1	0
				1	1	1	1	1

(Note) In case sending prohibited data, 0dB is set.

Mode	MSB			Bass/Treble Boost/Cut LS						
	D7	D6	D5	D4	D3	D2	D1	D0		
Boost	0	0	0		De	ss/Treble G	nin			
Cut	1	0	0		Da	iss/ rreble Ga	am			

:

:Initial condition

(6) About Power ON Reset

Built-in IC initialization is made during power on of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn on mute at the side being set until this initial data is sent.

Parameter	Symbol	Limit			Unit	Conditions	
Falameter	Symbol	Min	Тур	Max	Unit	Conditions	
Rise Time of VCC	trise	20	-	-	µsec	V_{CC} rise time from 0V to 3V	
VCC Voltage of Release Power ON Reset	VPOR	-	4.1	-	V		

(7) About External Compulsory Mute Terminal

It is possible to force mute externally by setting an input voltage to the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

Application Information

1. Function and Specifications

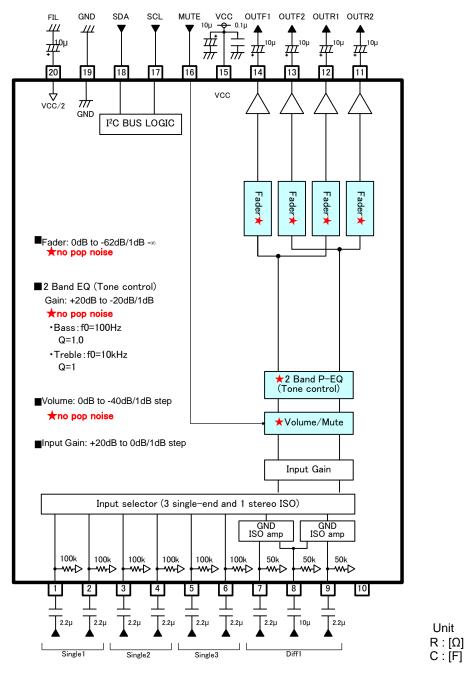
Function	Specifications
	Stereo 3 input
Input selector	Differential 1 input
Input gain	OdB to 20dB
Mute	Possible to use "Advanced switch" for prevention of switching noise.
Volume	· 0dB to -40dB (1dB step)
volume	Possible to use "Advanced switch" for prevention of switching noise.
	· -20dB to +20dB (1dB step)
Bass	• Q=1
Dass	• fo=100Hz
	Possible to use advanced switch at changing gain
	· -20dB to +20dB (1dB step)
Treble	• Q=1
Treble	· fo=10kHz
	Possible to use advanced switch at changing gain
Fader	• 0dB to -62dB(1dB step), -∞dB
Fauer	Possible to use "Advanced switch" for prevention of switching noise.

2. Volume / Fader Volume Attenuation Data

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
0	01	00	0	0	0	0	0	0	-32	01	00	1	0	0	0	0	0
-1			0	0	0	0	0	1	-33			1	0	0	0	0	1
-2			0	0	0	0	1	0	-34			1	0	0	0	1	0
-3			0	0	0	0	1	1	-35			1	0	0	0	1	1
-4			0	0	0	1	0	0	-36			1	0	0	1	0	0
-5			0	0	0	1	0	1	-37			1	0	0	1	0	1
-6			0	0	0	1	1	0	-38			1	0	0	1	1	0
-7			0	0	0	1	1	1	-39			1	0	0	1	1	1
-8			0	0	1	0	0	0	-40			1	0	1	0	0	0
-9			0	0	1	0	0	1	-41			1	0	1	0	0	1
-10			0	0	1	0	1	0	-42			1	0	1	0	1	0
-11	1		0	0	1	0	1	1	-43			1	0	1	0	1	1
-12	1		0	0	1	1	0	0	-44			1	0	1	1	0	0
-13	1		0	0	1	1	0	1	-45			1	0	1	1	0	1
-14	1		0	0	1	1	1	0	-46			1	0	1	1	1	0
-15	4	0	0	0	1	1	1	1	-47	1	0	1	0	1	1	1	1
-16	1	0	0	1	0	0	0	0	-48		0	1	1	0	0	0	0
-17			0	1	0	0	0	1	-49			1	1	0	0	0	1
-18			0	1	0	0	1	0	-50			1	1	0	0	1	0
-19			0	1	0	0	1	1	-51			1	1	0	0	1	1
-20			0	1	0	1	0	0	-52			1	1	0	1	0	0
-21			0	1	0	1	0	1	-53			1	1	0	1	0	1
-22			0	1	0	1	1	0	-54			1	1	0	1	1	0
-23			0	1	0	1	1	1	-55			1	1	0	1	1	1
-24			0	1	1	0	0	0	-56			1	1	1	0	0	0
-25			0	1	1	0	0	1	-57			1	1	1	0	0	1
-26			0	1	1	0	1	0	-58			1	1	1	0	1	0
-27			0	1	1	0	1	1	-59			1	1	1	0	1	1
-28			0	1	1	1	0	0	-60			1	1	1	1	0	0
-29]		0	1	1	1	0	1	-61			1	1	1	1	0	1
-30			0	1	1	1	1	0	-62			1	1	1	1	1	0
-31			0	1	1	1	1	1	-∞			1	1	1	1	1	1
For Volume	e atter	nuatio	n, only	y 0dB	to -40)dB ai	e ava	ilable									

: Initial condition

3. Application Circuit



Notes on Wiring

① Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.

- ② GND lines shall be one-point connected.
- ③ Wiring pattern of Digital should be away from that of Analog unit and cross-talk should not be acceptable.
- $\overset{\scriptstyle{(4)}}{4}$ SCL and SDA lines of I²C BUS should not be parallel if possible.
- The lines should be shielded, if they are adjacent to each other.

(5) Analog input lines should not be parallel if possible. The lines should be shielded, if they are adjacent to each other.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

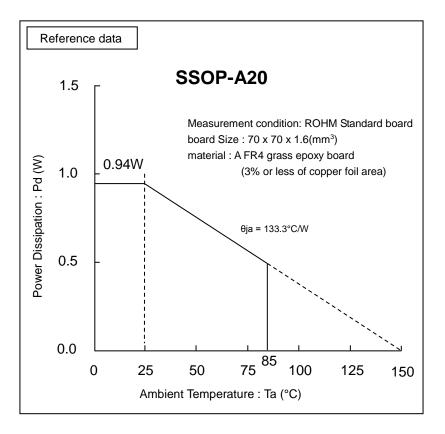


Figure 18. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25	VCC VOC VOC VOC VOC VOC VOC VOC	A terminal for signal input. The input impedance is 100kΩ(typ).
7 9	DP1 DP1	4.25		A terminal for positive input of ground isolation amplifier. The input impedance is 50kΩ(typ).
8	DN	4.25	VCC VCC VCC VCC VCC VCC VCC VCC	A terminal for negative input of ground isolation amplifier. The input impedance is 12.5kΩ(typ).
16	MUTE	-		A terminal for external compulsory mute. If terminal voltage is High level, the mute is off. And if the terminal voltage is Low level, the mute is on.
11 12 13 14	OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND GND	A terminal for fader and Subwoofer output.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

I/O Equivalence Circuits - continued

Terminal	Terminal	Terminal	Equivalent Circuit	Terminal Description
<u>No.</u> 15	Name VCC	Voltage 8.5		Power supply terminal.
17	SCL	-	VCC	A terminal for clock input of I ² C BUS communication.
18	SDA	-	VCC GND GND GND GND GND GND GND GND GND GND	A terminal for data input of I ² C BUS communication.
19	GND	0		Ground terminal.
20	FIL	4.25		Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

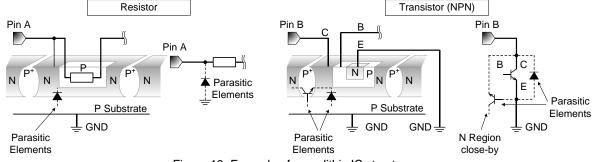
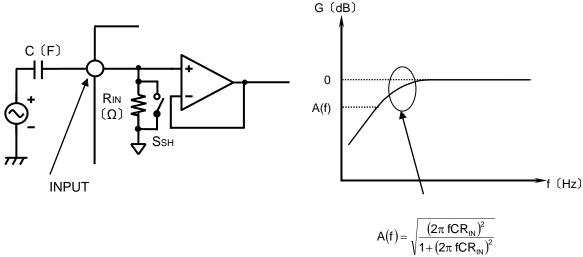


Figure 19. Example of monolithic IC structure

13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value

In the input signal terminal, please decide the constant value of the input coupling capacitor C(F) that would be sufficient to form an RC characterized HPF with input impedance $R_{IN}(\Omega)$ inside the IC.



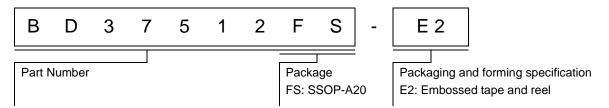
(b) About the Input Selector SHORT

SHORT mode is the command which makes switch $S_{SH} = ON$ of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

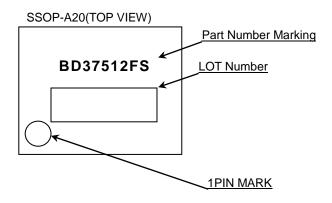
14. About Mute Terminal(Pin 16) when power supply is OFF

There should be no applied voltage across the Mute terminal (Pin 16) when power-supply is OFF. A resistor (about $2.2k\Omega$) should be connected in series to Mute terminal in case a voltage is supplied to Mute terminal. (Please refer Application Circuit Diagram.)

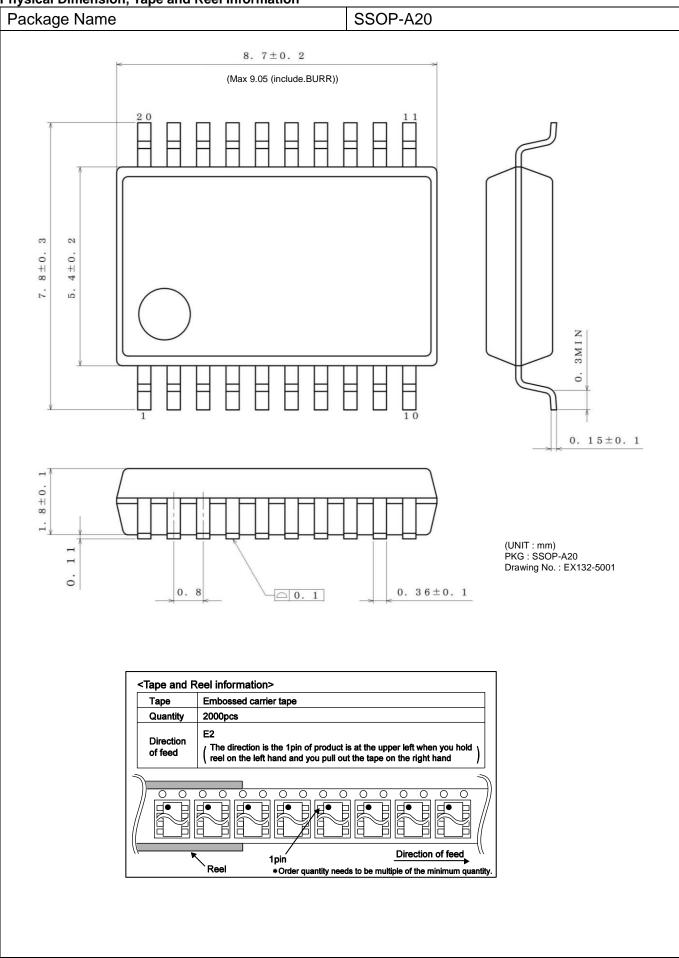
Ordering Information



Marking Diagram



Physical Dimension, Tape and Reel Information



Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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